

HSB88WA

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0587-0100 (Previous: ADE-208-965) Rev.1.00 Mar 31, 2005

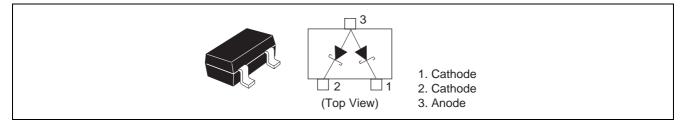
Features

- Low reverse current, Low capacitance.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB88WA	C7	СМРАК	PTSP0003ZB-A (CMPAK)

Pin Arrangement





Absolute Maximum Ratings

$(Ta = 25^{\circ}C)$ Symbol Value Unit ltem Reverse voltage V_R 10 V lo *¹ Average rectified current 15 mΑ 125 °C Junction temperature Tj °C Storage temperature Tstg -55 to +125

Note: 1. Per one device.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

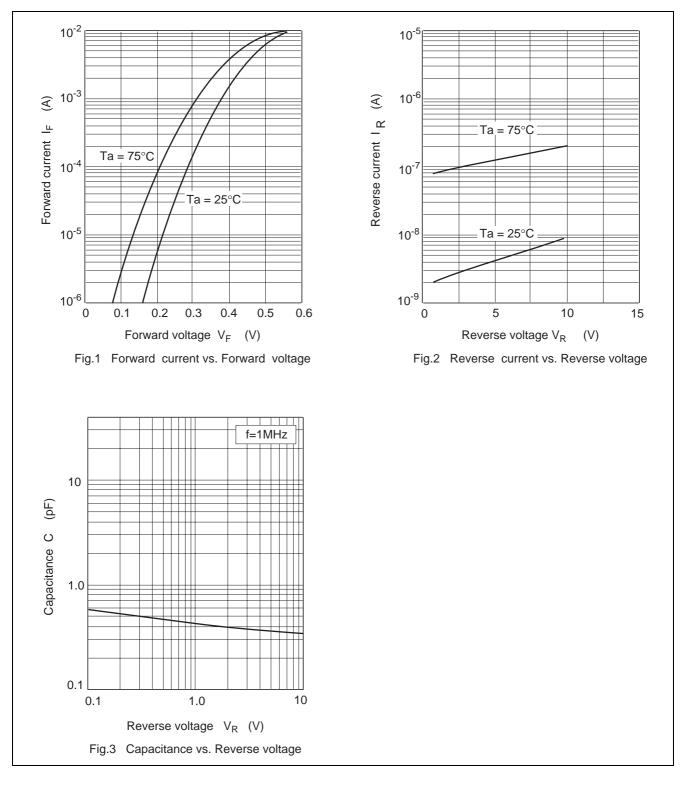
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	0.350	-	0.420	V	I _F = 1 mA
	V _{F2}	0.500	-	0.580		I _F = 10 mA
Reverse current	I _{R1}			0.2	μA	V _R = 2 V
	I _{R2}	_	_	10		V _R = 10 V
Capacitance	С	_	-	0.80	pF	V _R = 0 V, f = 1 MHz
Capacitance deviation	ΔC	_	-	0.10	pF	V _R = 0 V, f = 1 MHz
Forward voltage deviation	ΔV_{F}	-	-	10	mV	I _F = 10 mA
ESD-Capabilityme *2	—	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward
						and reverse direction 1 pulse.

Notes: 1. Per one device.

2. Failure criterion ; $I_R>0.4~\mu A$ at V_R = 2V

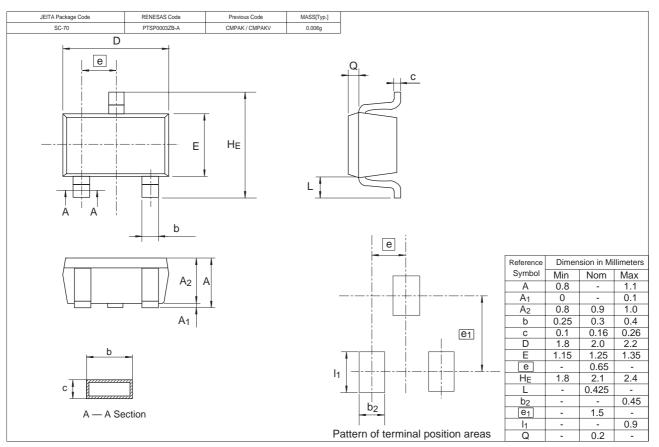


Main Characteristic





Package Dimensions





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